

Please amend the claims as follows.

9. (amended) The semiconductor package according to claim 2, wherein said first insulating substrate is a laminated sheet lined with copper on said one surface and on said opposite surface.

12. (amended) The semiconductor package according to claim 4, wherein said first insulating substrate is a laminated sheet lined with copper on said one surface and on said opposite surface.

13. (amended) A semiconductor package comprising:

a first insulating substrate carrying a mounting portion for mounting a semiconductor device and a first electrically conductive pattern electrically connected to said semiconductor device;

a sidewall section formed upright around said mounting portion of said first insulating substrate;

a cavity defined by said first insulating substrate and the sidewall section and encapsulated by encapsulating resin as said semiconductor device is mounted on said mounting portion; and

a second insulating substrate provided in said cavity and on said sidewall section and carrying a second electrically conductive pattern electrically connected to said first

electrically conductive pattern via through-holes formed in said sidewall section;

wherein solder lands are provided at least in said cavity on one surface of said first insulating substrate,

wherein said second insulating substrate is a laminated sheet lined on one side with copper,

wherein said encapsulating resin is planarized.